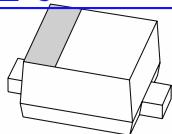


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# PMEG4002EB

0.2 A very low  $V_F$  MEGA Schottky barrier rectifier in SOD523 package

Rev. 02 — 13 January 2010

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small and flat lead Surface Mounted Device (SMD) plastic package.

### 1.2 Features

- Forward current: 200 mA
- Reverse voltage: 40 V
- Very low forward voltage
- Ultra small and flat lead SMD plastic package

### 1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Inverse polarity protection
- Low power consumption applications

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_F$	forward current		-	-	200	mA	
$V_R$	reverse voltage		-	-	40	V	
$V_F$	forward voltage	$I_F = 200$ mA	[1]	-	520	600	mV

[1] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .



## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	cathode	[1]	
2	anode		1  2 sym001

[1] The marking bar indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4002EB	SC-79	plastic surface mounted package; 2 leads	SOD523

## 4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG4002EB	L9

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage		-	40	V
$I_F$	forward current		-	200	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1 \text{ s}; \delta \leq 0.5$	-	300	mA
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8.3 \text{ ms half sine wave; JEDEC method}$	-	1	A
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	450 K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses. Nomograms for determining the reverse power losses  $P_R$  and  $I_{F(AV)}$  rating will be available on request.

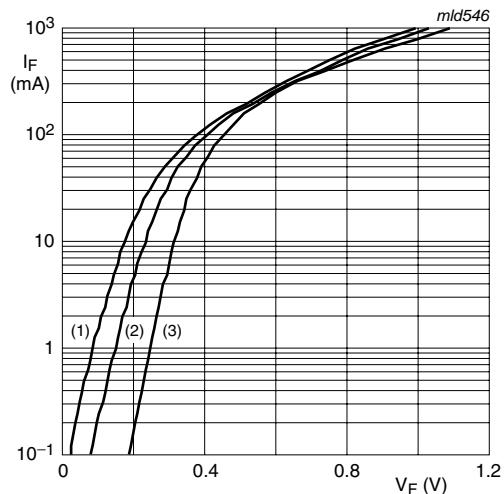
## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25^\circ\text{C}$  unless otherwise specified.

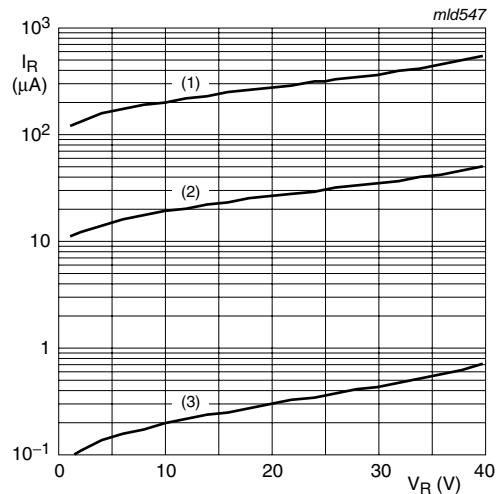
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 0.1 \text{ mA}$	-	190	220	mV
		$I_F = 1 \text{ mA}$	-	250	290	mV
		$I_F = 10 \text{ mA}$	-	320	360	mV
		$I_F = 100 \text{ mA}$	-	440	500	mV
		$I_F = 200 \text{ mA}$	-	520	600	mV
$I_R$	reverse current	$V_R = 25 \text{ V}$	[1]	-	-	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}$	-	-	20	pF

[1] Pulse test:  $t_p \leq 300 \mu\text{s}$ ;  $\delta \leq 0.02$ .



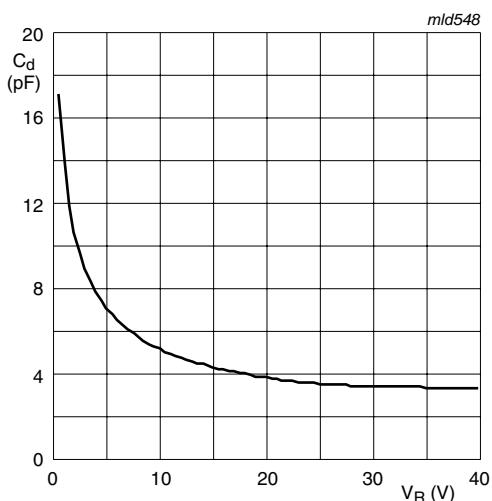
- (1)  $T_{amb} = 125 \text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = 85 \text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = 25 \text{ }^{\circ}\text{C}$

**Fig 1. Forward current as a function of forward voltage; typical values**



- (1)  $T_{amb} = 125 \text{ }^{\circ}\text{C}$
- (2)  $T_{amb} = 85 \text{ }^{\circ}\text{C}$
- (3)  $T_{amb} = 25 \text{ }^{\circ}\text{C}$

**Fig 2. Reverse current as a function of reverse voltage; typical values**



$T_{amb} = 25 \text{ }^{\circ}\text{C}; f = 1 \text{ MHz}$

**Fig 3. Diode capacitance as a function of reverse voltage; typical values**

## 8. Package outline

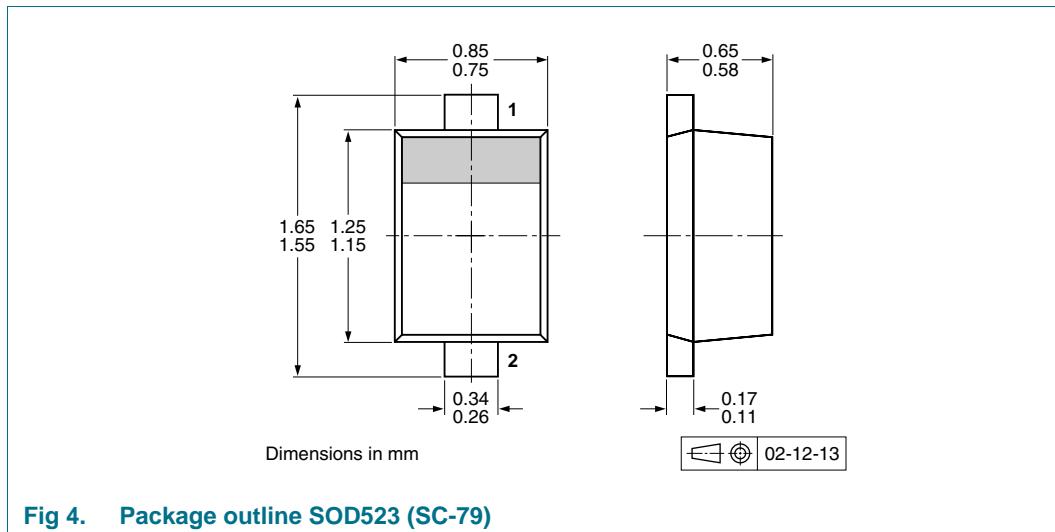


Fig 4. Package outline SOD523 (SC-79)

## 9. Packing information

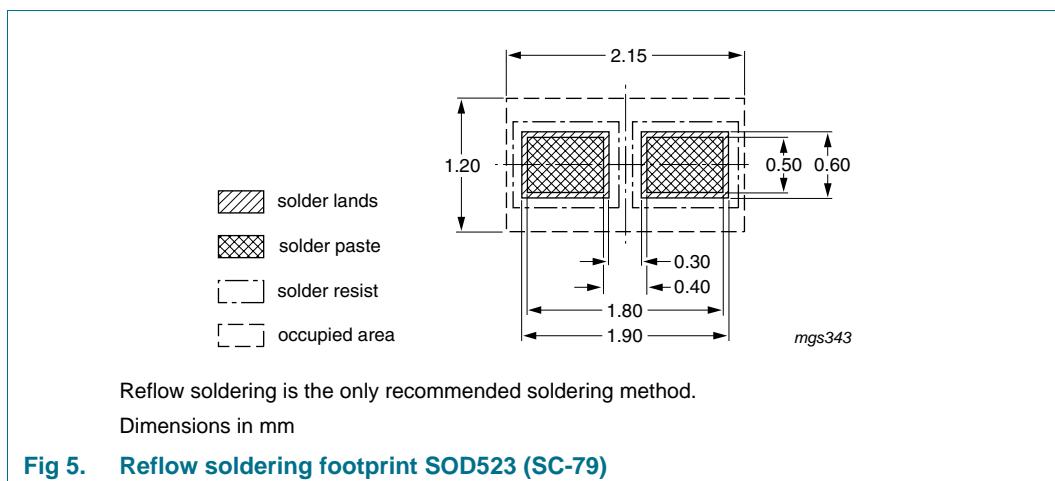
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity	
			3000	10000
PMEG4002EB	SOD523	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 13](#).

## 10. Soldering



Reflow soldering is the only recommended soldering method.

Dimensions in mm

Fig 5. Reflow soldering footprint SOD523 (SC-79)

## 11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4002EB_2	20100113	Product data sheet	-	PMEG4002EB_1
Modifications:	<ul style="list-style-type: none"><li>This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li><li><a href="#">Figure 5 "Reflow soldering footprint SOD523 (SC-79)": updated</a></li></ul>			
PMEG4002EB_1	20050712	Product data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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